



PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Koji FURUSAWA

Serial No. 09/939,761

GROUP 2815

Filed August 28, 2001

Examiner Edgardo Ortiz

SEMICONDUCTOR DEVICE

AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of February 15, 2002,
please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 1, replace the paragraph, beginning on line 22,
bridging pages 1 and 2, as follows:

Q1
--Since the bonding pad on the substrate is provided
around the semiconductor chip in the lowermost layer, the upper
layer semiconductor chip with a smaller chip size has a longer
distance with respect to the bonding pad on the substrate.
Therefore, with a larger chip size difference in the upper layer
and the lower layer, the distance between the bonding pad of the
upper layer semiconductor chip and the bonding pad on the
substrate becomes longer. In particular, the wire connecting the
substrate to the chip becomes longer. Accordingly, the wire
strength is lowered so that sagging of the wire by its own weight
occurs. Tilting of the wire at the time of sealing, or the like

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Jules